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August 2014

FCD5N60 / FCU5N60 N-Channel SuperFET MOSFET 600 V, 4.6 A, 950 m Ω

Features

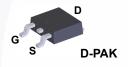
- 650 V @ T_J = 150°C
- Typ. $R_{DS(on)}$ = 810 m Ω
- Ultra Low Gate Charge (Typ. Q_q = 16 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 32 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

Application

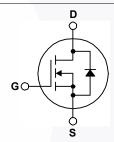
- · LCD/LED TV and Monitor
- Lighting
- · Solar Inverter
- AC-DC Power Supply

Description

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.







MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCD5N60TM FCD5N60TM_WS FCU5N60TU	Unit	
V_{DSS}	Drain to Source Voltage			600	V	
. \	Drain Current	- Continuous (T _C = 25°C)		4.6	A	
ID	Diam Current	- Continuous (T _C = 100°C)		2.9		
I _{DM}	Drain Current	- Pulsed (N	Note 1)	13.8	Α	
V_{GSS}	Gate to Source Voltage			±30	V	
E _{AS}	Single Pulsed Avalanche Ener	gy (M	Note 2)	159	mJ	
I _{AR}	Avalanche Current	1)	Note 1)	4.6	Α	
E _{AR}	Repetitive Avalanche Energy	1)	Note 1)	5.4	mJ	
dv/dt	Peak Diode Recovery dv/dt	1)	Note 3)	4.5	V/ns	
n	Davisa Dissipation	$(T_C = 25^{\circ}C)$		54	W	
P_{D}	Power Dissipation - Derate Above 25°C			0.43	W/°C	
T _J , T _{STG}	Operating and Storage Tempe	rature Range		-55 to +150	οС	
T _L	Maximum Lead Temperature f	or Soldering, 1/8" from Case for 5 Secor	nds	300	°C	

Thermal Characteristics

Symbol	Parameter	FCD5N60TM FCD5N60TM_WS FCU5N60TU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	83	*C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCD5N60TM	FCD5N60	D-PAK	Tape and Reel	330 mm	16 mm	2500 units
FCD5N60TM_WS	FCD5N60	D-PAK	Tape and Reel	330 mm	16 mm	2500 units
FCU5N60TU	FCU5N60	IPAK	Tube	N/A	N/A	75 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_C = 25^{\circ}\text{C}$	600	-	-	V
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_C = 150^{\circ}\text{C}$	-	650	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.6	-	V/°C
BV _{DS}	Drain to Source Avalanche Breakdown Voltage	V _{GS} = 0 V, I _D = 4.6 A	-	700	-	V
	Zoro Coto Voltago Proin Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1	
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μΑ
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 2.3 \text{ A}$	-	0.81	0.95	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 2.3 \text{ A}$	-	3.8	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	470	600	pF
C _{oss}	Output Capacitance		-	250	320	pF
C _{rss}	Reverse Transfer Capacitance		-	22	-	pF
C _{oss}	Output Capacitance	V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz	-	12	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	32	-	pF

Switching Characteristics

_						
t _{d(on)}	Turn-On Delay Time		-/	12	30	ns
t _r	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_D = 4.6 \text{ A},$	-	40	90	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{G} = 25 \Omega$	/-	47	95	ns
t _f	Turn-Off Fall Time	(Note 4	-	22	55	ns
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 480 V, I _D = 4.6 A,	-	16	-	nC
Q_{gs}	Gate to Source Gate Charge	V _{DS} = 480 V, I _D = 4.6 A, V _{GS} = 10 V	-	2.8	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4	_	7	_	nC

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	4.6	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	13.8	Α
V_{SD}	Drain to Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_{SD} = 4 \text{ V}$	I.6 A -	-	1.4	V
t _{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V, } I_{SD} = 4$	1.6 A	295	-	ns
Q_{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V, } I_{SD} = 4 \text{ Reverse Recovery Charge}$ Reverse Recovery Charge $dI_F/dt = 100 \text{ A/}\mu\text{s}$	_	2.7	-	μC

Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I_{AS} = 2.3 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C.
- 3. I $_{SD} \leq$ 4.6 A, di/dt \leq 200 A/ $\mu s,~V_{DD} \leq$ BV $_{DSS},$ starting T $_{J}$ = 25°C.
- Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

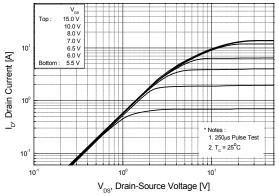
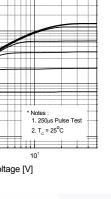


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage**



10¹

10⁰

10⁻¹

Drain Current [A]

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

V_{GS} , Gate-Source Voltage [V]

-55°C

Note 1. V_{DS} = 40V

2. 250us Pulse Test

10

Figure 2. Transfer Characteristics

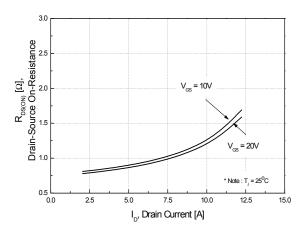
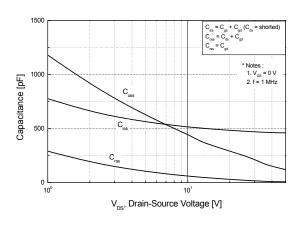
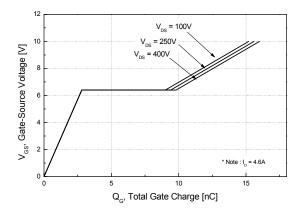


Figure 5. Capacitance Characteristics



10 Drain Current [A] 150°C 10 -55°C Note 1. V_{ps} = 40V 2. 250µs Pulse Test 4 8 10 $V_{_{\!G\!S}}$, Gate-Source Voltage [V]

Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

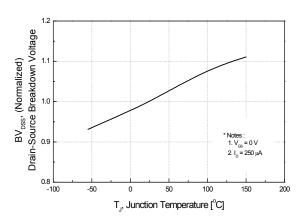


Figure 8. On-Resistance Variation vs. Temperature

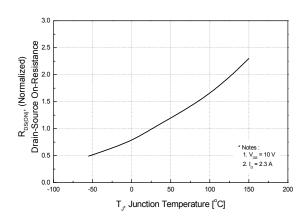


Figure 9. Maximum Safe Operating Area

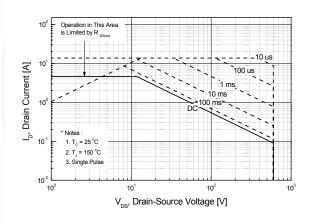


Figure 10. Maximum Drain Current vs. Case Temperature

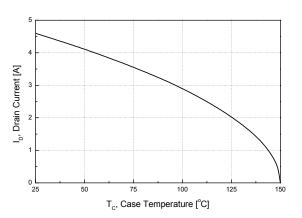
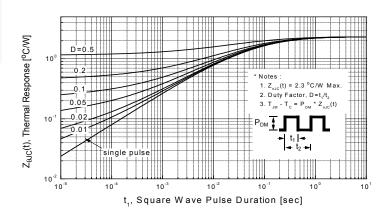


Figure 11. Transient Thermal Response Curve



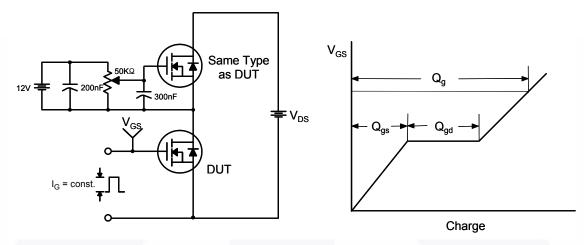


Figure 12. Gate Charge Test Circuit & Waveform

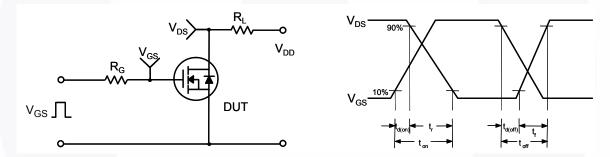


Figure 13. Resistive Switching Test Circuit & Waveforms

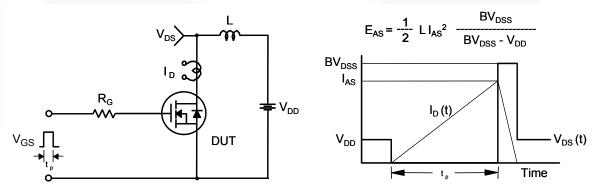


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

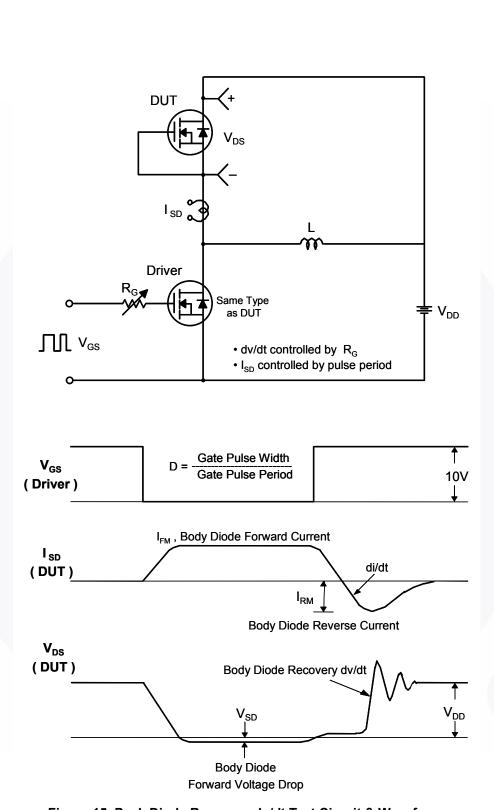


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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